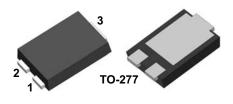
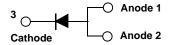
September 2018

# FSV2050V 20 A, 50 V Ultra Low VF Schottky Rectifier

#### **Features**

- Ultra Low Forward Voltage Drop
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- RoHS Compliant
- Green Molding Compound as per IEC61249 Standard
- Lead Free in Compliance with EU RoHS 2011/65/EU Directive
- Qualified with Reflow (J-STD-020) and Solder Temperature 260°C Classification





## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
FSV2050V	FSV2050V	TO-277 3L	Tape and Reel

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter	Value	Unit
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	50	V
$V_{RWM}$	Working Peak Reverse Voltage	50	V
V <sub>RMS</sub>	RMS Reverse Voltage	35	V
$V_{R}$	DC Blocking Voltage	50	V
I <sub>F(AV)</sub>	Average Rectified Peak Forward Surge Current	20	Α
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current	320	Α
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics(1)

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	100	40	°C/W
Ψлг	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	°C/W
	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	C/VV

#### Note:

1. The thermal resistances ( $R_{\theta JA} \& \psi_{JL}$ ) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



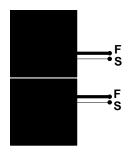


Figure 1. Minimum Land Pattern of 2 oz Copper

Figure 2. Maximum Land Pattern of 2 oz Copper

#### **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$BV_R$	Breakdown Voltage	I <sub>R</sub> = 500 μA	50	55.3		V
V <sub>F</sub>	Forward Voltage Drop	I <sub>F</sub> = 20 A		485	550	mV
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 50 V		60.3	320	μΑ

# **Typical Performance Characteristics**

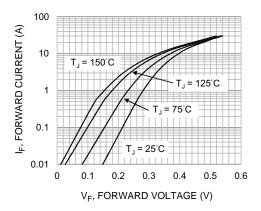
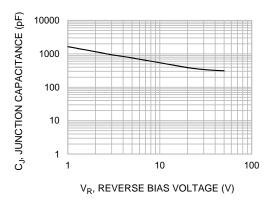


Figure 3. Typical Forward Characteristics



**Figure 5. Typical Junction Capacitance** 

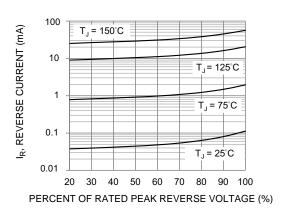
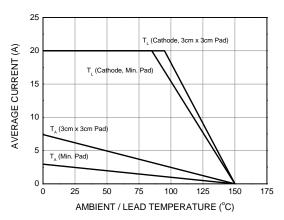
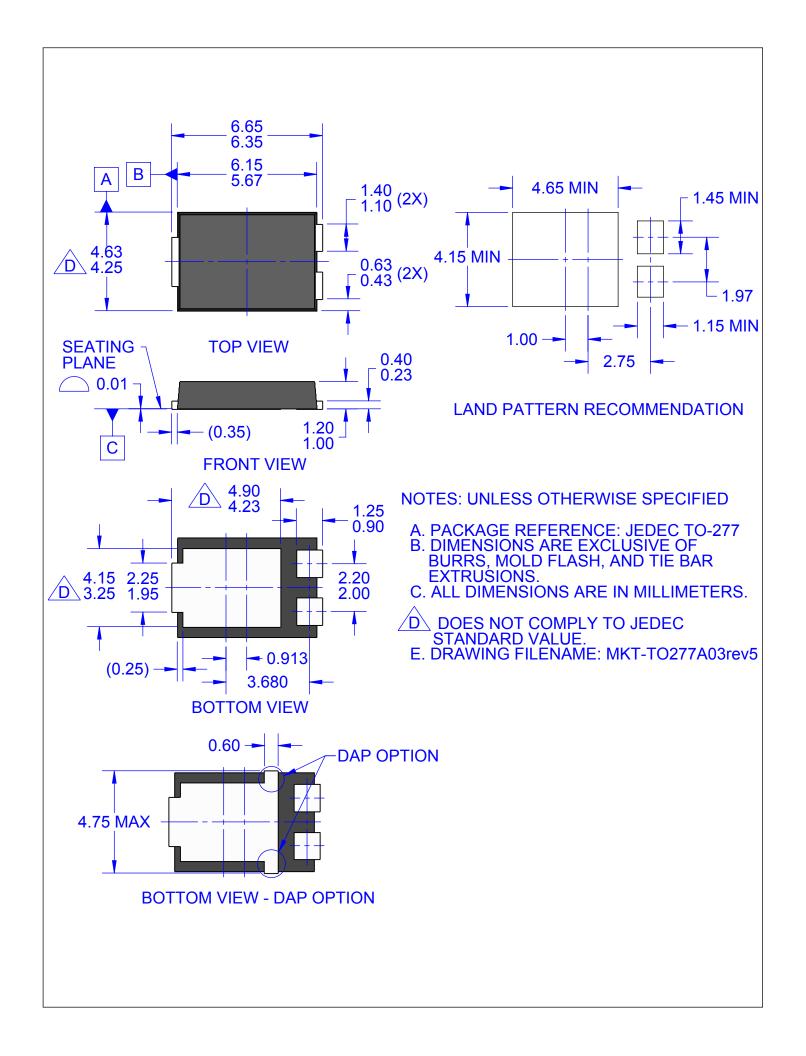


Figure 4. Typical Reverse Characteristic



**Figure 6. Forward Current Derating Curve** 



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